

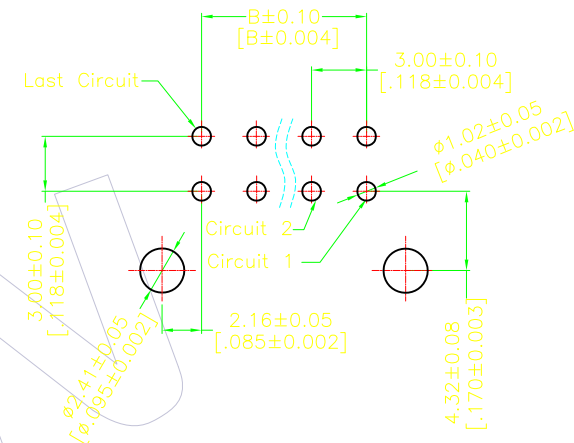
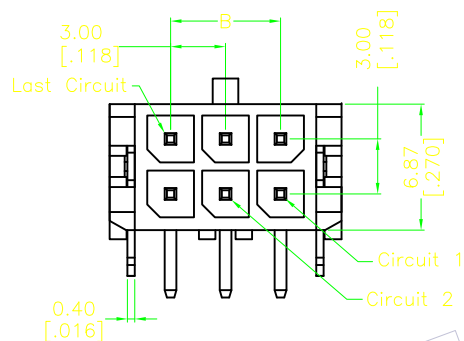
HSF

NOTES:

Current Rating:5.0A AMP
 Contact Resistance:10milliohm Max
 Withstand Voltage:1000V AC/Minute
 Insulation Resistance:1000Megohm Min
 Operation Temperature:-25°C to +85°C

Housing Material:LCP+30%GF(UL94V-0)
 Contact Material:Copper alloy
 Contact plating:Au/Sn over Ni Plating

RECOMMENDED PCB LAYOUT
 TOLERANCE IS ±0.05



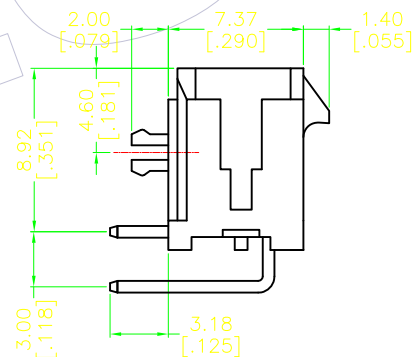
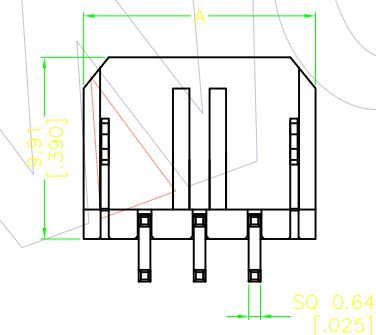
Ordering Information

WF3001-2 WR XX B X 2

Terminal shape:
WR:Wafer 90° DIP

NO.of Pins Per Row:01~12Pin

Packing:
 0=PE Bag
 T=Tube
 A=Tray
 R=Tape&Reel



Circuit	A	B
02	6.65 [0.262]	NA
04	9.65 [0.380]	3.00 [0.118]
06	12.65 [0.498]	6.00 [0.236]
08	15.65 [0.616]	9.00 [0.355]
10	18.65 [0.735]	12.00 [0.473]
12	21.65 [0.853]	15.00 [0.591]
14	24.65 [0.971]	18.00 [0.709]
16	27.65 [1.089]	21.00 [0.827]
18	30.65 [1.207]	24.00 [0.945]
20	33.65 [1.325]	27.00 [1.063]
22	36.65 [1.443]	30.00 [1.181]
24	39.65 [1.561]	33.00 [1.299]

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	PART NO.
A1	2012.05.04	料号由WF3001-2WRHXXBX2变更为WF3001-2WRXXBX2	Atomy	X.X ±0.40	FZY	2012.05.04	1:1	△ WF3001-2WRXXBX2
A0	2011.12.20	NEW	-	X.XX ±0.25	CHECK	DATE	mm inch	TITLE: 3.00 WAFER DUAL ROW 90° DIP WITH CLIP
				X.XXX ±0.15	APPROVE	DATE	A4	Customer NO.
				Angle ± 3°			1/1	
				DIM TOL			SHEET	
							PROJ.	